



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



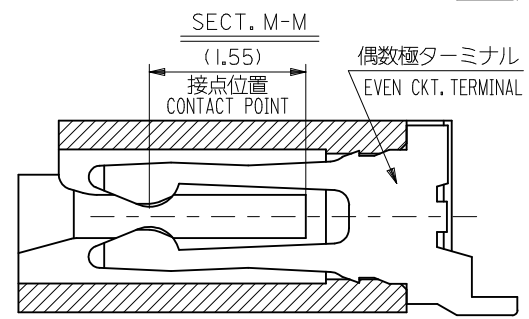
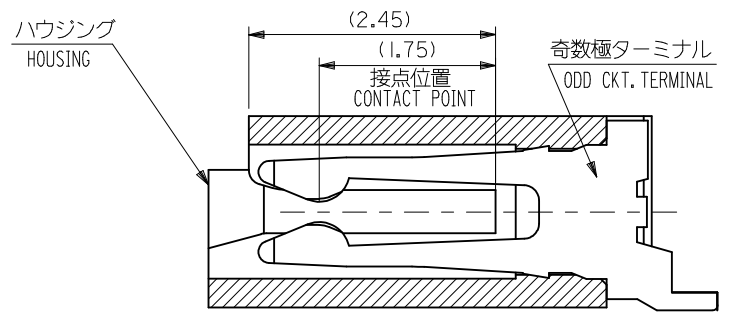
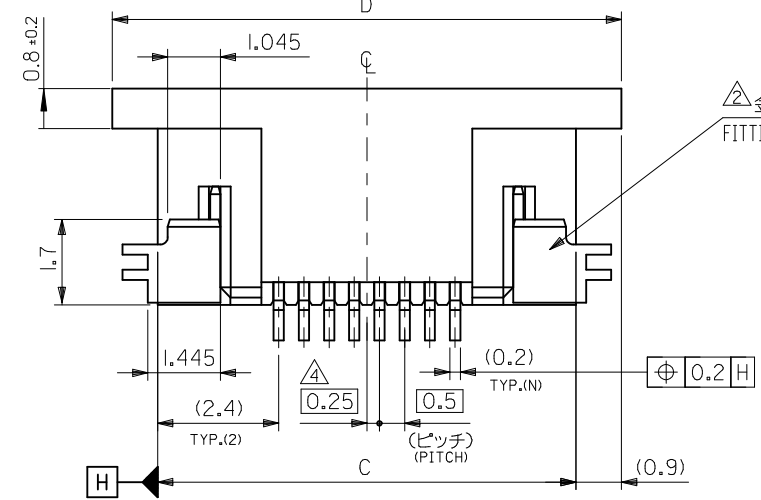
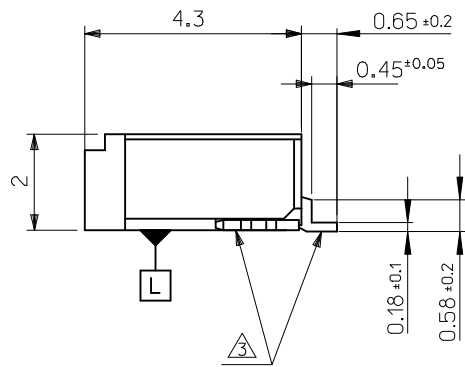
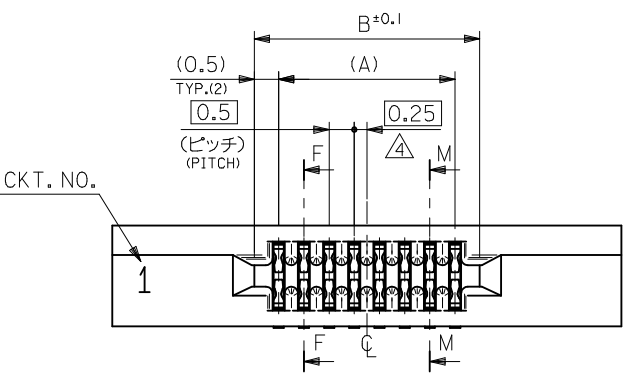
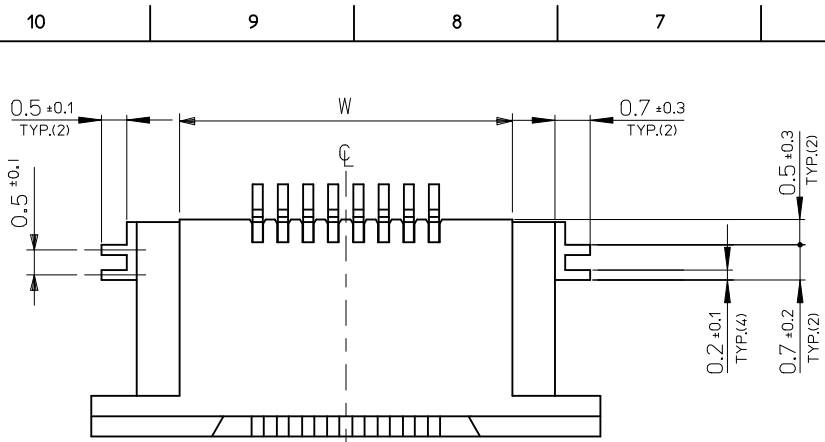
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

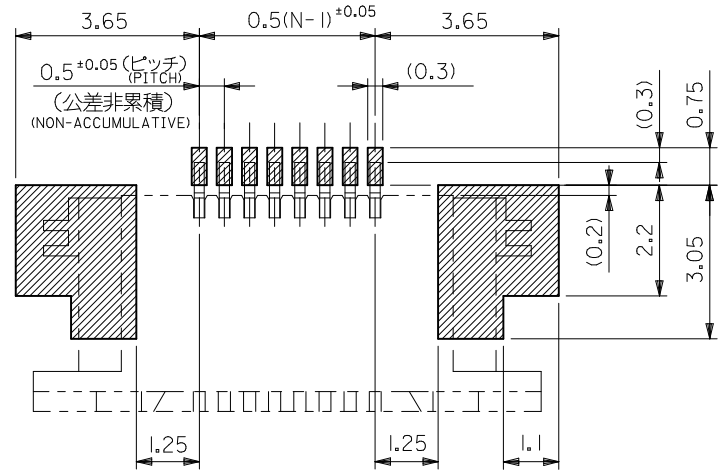




- 注記(NOTES)
1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
 2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX. 下方向 0.15MAX. とする。
 3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

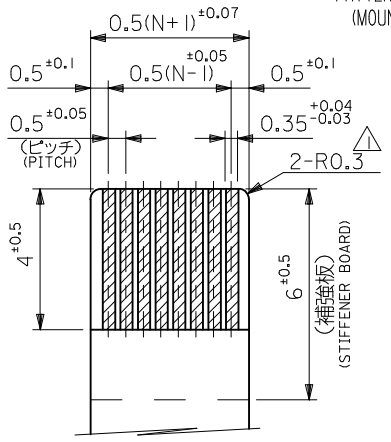
MODEL NO. 52689-***49

REVISED EC NO.: J2017-0300 DRWNGS CHKD: APPR: MSASAO	2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
		0.25 OVER	0.5 UNDER	±	CHECKED BY K. TOJO	DATE '04/02/03	DOCUMENT NO. SD-52689-034		
		0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/02/03			
		0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE SHEET 2		SHEET NO. 1 OF 2		
		10 OVER	30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
		30 OVER		±0.3					
G		ANGULAR		±3 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

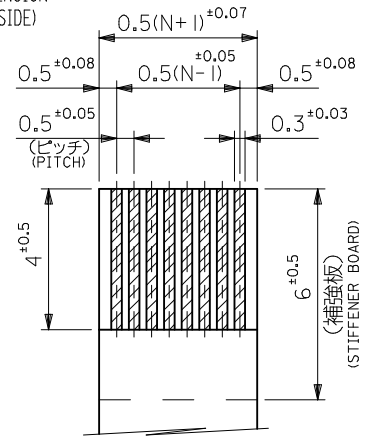


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

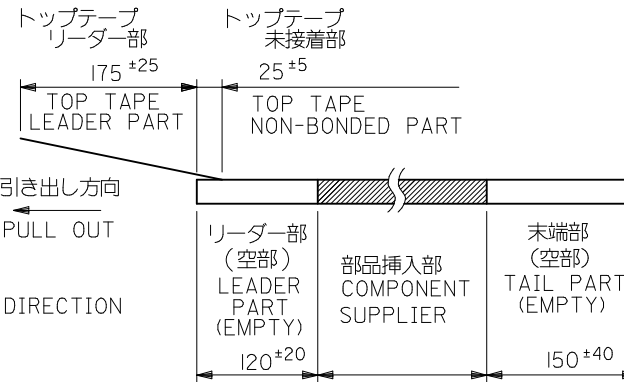
△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
	13.6	17.1	15.3	11.5	10.5	ORDER No. オーダー番号	52689-2287	52689-2249

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±	0.25 OVER 0.5 UNDER ±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		0.5 OVER 1.0 UNDER ±	0 OVER 10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/03				
		10 OVER 30 UNDER ±0.25	30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/02/03				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

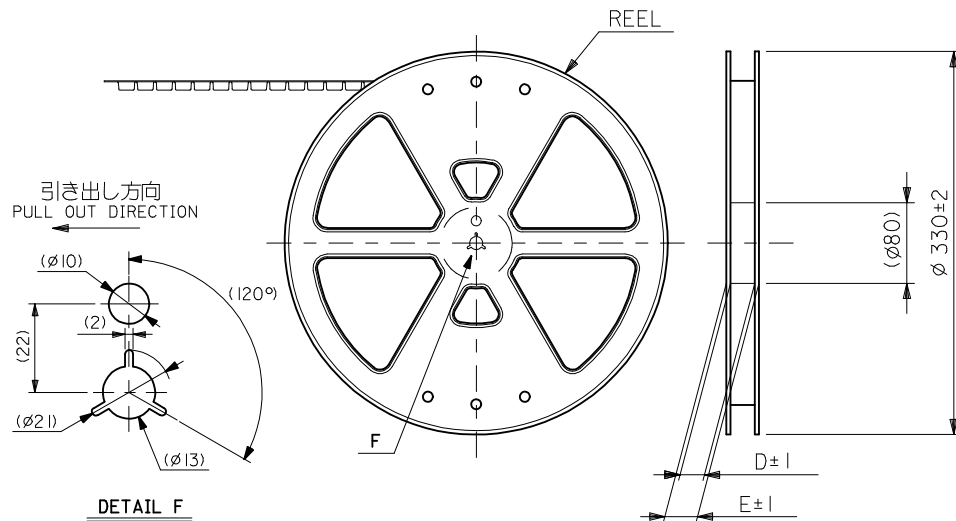
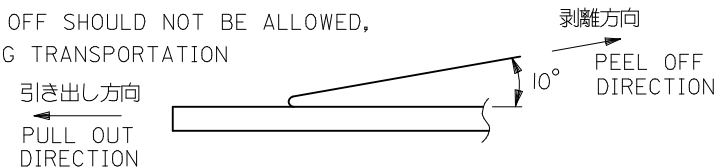
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

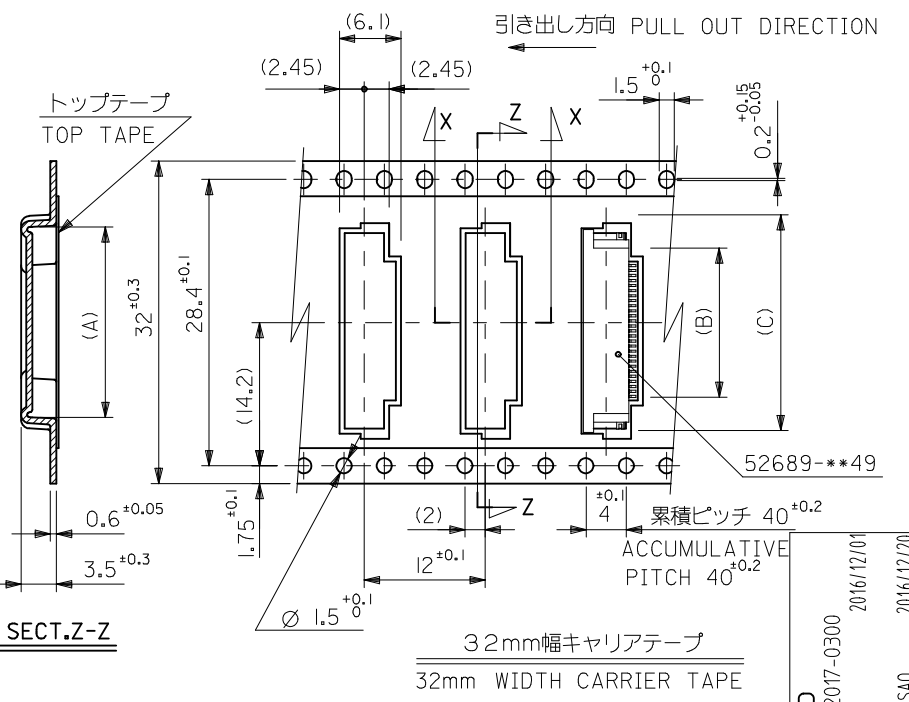
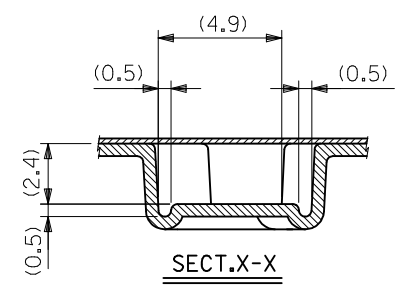
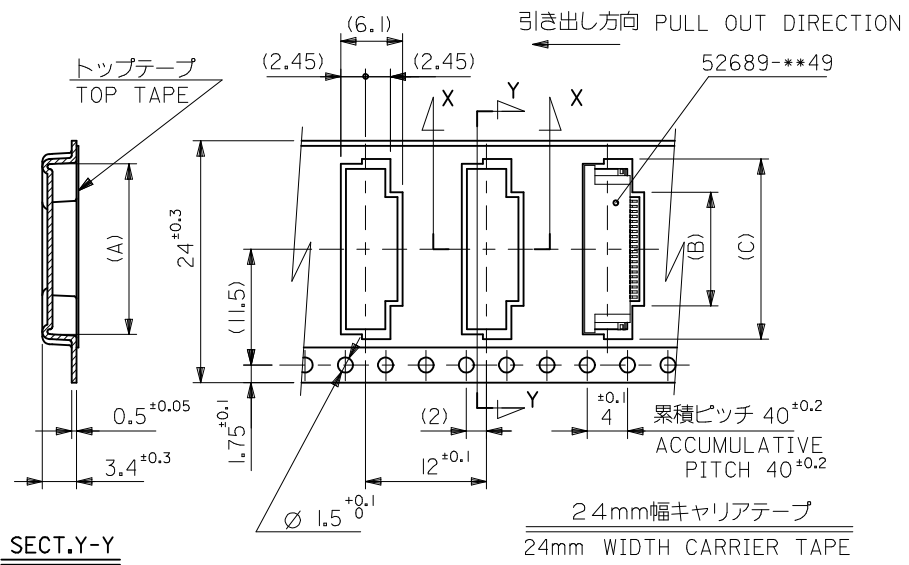
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

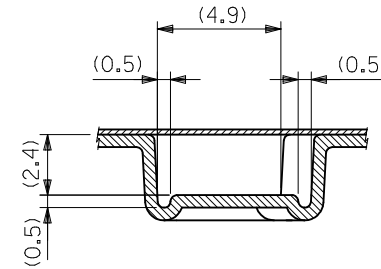
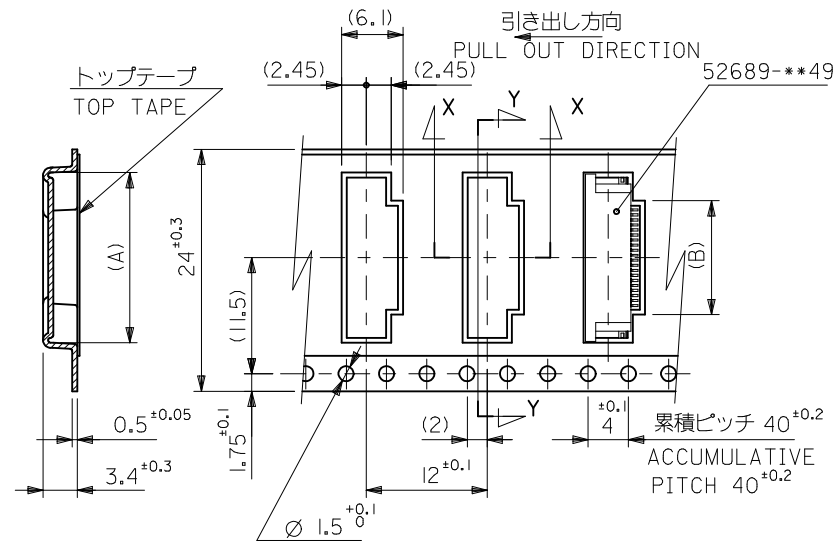
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	DOCUMENT NO. SD-52689-035	SHEET NO. 1 OF 3
0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K.TOJO	DATE 2004/02/03	MATERIAL NO. SEE SHEET 2,3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M.SASAO	DATE 2004/02/03					
1.0 OVER	10 UNDER	±0.2							
10 OVER	30 UNDER	±0.25							
30 OVER		±0.3							
		ANGULAR	±3						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3				



52689-**-87	32	37.4	33.4	22.4	15.8	21.4	52689-3087	30
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
	MM ONLY		---		METRIC		◎ □		
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE			
	0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-			
	0.5 OVER	1.0 UNDER	±0.1	K.TOJO	2004/02/03				
1.0 OVER	10 UNDER	±0.2	APPROVED BY		DATE	molex DOCUMENT NO. SD-52689-035 SHEET NO. 2 OF 3			
10 OVER	30 UNDER	±0.25	M.SASAO		2004/02/03				
30 OVER		±0.3	MATERIAL NO.						
ANGULAR		±	SEE TABLE						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			A3						



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO. 極数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWN BY: 2016/12/14 CHKD: 2016/12/20 APPR: MSASAO	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	K. TOJO	2004/02/03			
1.0 OVER	10 UNDER	±0.2	M. SASAO	2004/02/03	MATERIAL NO.			
30 OVER		±0.3	SEE TABLE		SD-52689-035		3 OF 3	
ANGULAR ±3				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		